

In the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently Amended) An optical sensor circuit assembly, comprising:
an optically transmissive substrate including filter material;
an electrical circuit on a first surface of the optically transmissive substrate, the electrical circuit including electrically conductive leads;
an integrated circuit including an optical imaging element located on a face of the integrated circuit facing the substrate and electrically conductive pads on a face of the integrated circuit, the optical imaging element spaced away from the first surface of the optically transmissive substrate; and
an optically transmissive medium filling space between the integrated circuit and the optically transmissive substrate, said optically transmissive medium acting as an environmental seal for the face of the integrated circuit facing the substrate;
integrated circuit electrically coupled to and mounted directly on the electrical circuit disposed on the substrate by an electrical connection between the electrically conductive pads on the face of the integrated circuit and the electrically conductive leads of the electrical circuit on the substrate.
2. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the filter material is embedded in said substrate.
3. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the filter material is dispersed in said substrate.
4. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the filter material is a thin film layer on the substrate.

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5. (Original) The optical sensor circuit assembly of claim 4, wherein said thin film layer further comprises material having antireflective properties.

6. (Canceled).

7. (Canceled).

8. (Previously Presented) The optical sensor circuit assembly of claim 1, wherein the optical imaging element is electrically coupled to the electrical circuit by electrically conductive bumps disposed between the leads and the pads.

9. (Original) The optical sensor circuit assembly of claim 1, further comprising at least one optical element positioned to direct electromagnetic radiation through said substrate and filter material and to said optical imaging element.

10.-20. (Canceled).

21. (Previously Presented) The optical sensor circuit assembly of claim 1, further comprising a lens mount supporting a lens coupled to a second surface of the optically transmissive substrate opposite the first surface of the optically transmissive substrate.